

A scalable model based RTL framework zamiaCAD for static analysis

Tšepurov, Anton; Jenihhin, Maksim; Raik, Jaan; Tihhomirov, Valentin 2012 IEEE/IFIP 20th International Conference on VLSI and System-on-Chip (VLSI-SoC) : October 7-10, 2012 Santa Cruz, USA Dream Inn, Santa Cruz, USA : [proceedings] 2012 / p. 171-176 : ill <https://www.semanticscholar.org/paper/A-scalable-model-based-RTL-framework-zamiaCAD-for-Tsepurov-Bartsch/d19eefa44f793621d537c06498784e06e0332fd2>

Accelerating transient fault injection campaigns by using Dynamic HDL Slicing

Bagbaba, Ahmet Cagri; Jenihhin, Maksim; Raik, Jaan; Sauer, Christian 2019 IEEE Nordic Circuits and Systems Conference (NORCAS) : NORCHIP and International Symposium of System-on-Chip (SoC), 29-30 October 2019, Helsinki, Finland : proceedings in IEEE Xplore 2019 / 7 p. : ill <https://doi.org/10.1109/NORCHIP.2019.8906932>

Efficient fault injection based on dynamic HDL slicing technique

Bagbaba, Ahmet Cagri; Jenihhin, Maksim; Raik, Jaan; Sauer, Christian 2019 IEEE 25th International Symposium on On-Line Testing and Robust System Design (IOLTS 2019) : 1-3 July 2019, Greece 2019 / p. 52-53 : ill <https://doi.org/10.1109/IOLTS.2019.8854419>

Extensible open-source framework for translating RTL VHDL IP cores to SystemC

Saif Abrar, Syed; Jenihhin, Maksim; Raik, Jaan Proceedings of the 2013 IEEE 16th International Symposium on Design and Diagnostics of Electronic Circuits & Systems (DDECS) : April 8-10, 2013, Karlovy Vary, Czech Republic 2013 / p. 112-115

Mutation analysis for systemC designs at TLM

Guarnieri, Valerio; Bombieri, Nicola; Pravadelli, Graziano; Fummi, Franco; **Hantson, Hanno; Raik, Jaan; Jenihhin, Maksim; Ubar, Raimund-Johannes** 12th IEEE Latin American Test Workshop (LATW) : Porto de Galinhas, Brasil, 27-30 March 2011 2011 / [6] p <https://ieeexplore.ieee.org/document/5985925>

Simulation-based equivalence checking between IEEE 1687 ICL and RTL

Damljanovic, Aleksa; **Jutman, Artur**; Portolan, Michele; Tšertov, Anton 2019 IEEE International Test Conference (ITC) 2019 / paper. 7.3, 8 p. : ill <https://doi.org/10.1109/ITC44170.2019.9000181>